

RF7245 Release Qualification Report

Page 1 of 1

Product Description	3 V W-CDMA BAND 5 LINEAR PA MODULE				
Package Type	Laminate Module, 3 x 3 x 1.0mm	Process Technology	InGaP		
Qualification #	10-Qual-1428	Date Issued	3/28/2011		

FOR IMPORTANT INFORMATION REGARDING THESE MATERIALS INCLUDING DISCLAIMERS REGARDING USE IN CERTAIN APPLICATIONS, SEE THE <u>STANDARD DISCLAIMER</u> FOR PRODUCT DOCUMENTS WHICH CAN ALSO BE FOUND AT <u>WWW.RFMD.COM</u>

Test Name	Test Standard and Conditions	# Samples x # Lots	Test Results			
High Temperature Operating Life	JESD22-A108, 1000 hrs	77 x 3 lots	Pass			
Temperature Humidity with Bias	JESD22-A101, 1000 hrs	77 x 3 lots	Pass			
ESD Human Body Model	ANSI/ESDA/JEDEC JS-001-2010	3 x 1 lot	Pass		Class 1C	
ESD Charge Device Model	JESD22-C101	3 x 1 lot	Pass		Class III	
Moisture Sensitivity Level	IPC/JEDEC J-STD-020	77 x 3 lots	Pass	MSL 3	260°C	
Temperature Cycling	JESD22-A104, 1000 cycles Condition G (-40°C/+125°C), Soak Mode 2	77 x 3 lots loose piece	Pass		Preconditioned MSL 3 260°C	
Temperature Cycling	JESD22-A104, 1000 cycles Condition G (-40°C/+125°C), Soak mode 2, Preconditioning per JESD22-A113	77 x 3 lots on boards	Pass		Preconditioned MSL 3 260°C	
High Temperature Storage	JESD22-A103, 1000 hours Condition B (150°C)	77 x 3 lots	Pass			
Unbiased HAST	JESD22-A110, 96 hours 130C, 85%RH, 33.3psia	77 x 3 lots	Pass			
Solderability	JESD22-B102 Condition E (16 hr Dry Bake)	77 x 3 lots	Pass			
Characterization	Data Sheet	10 x 3 lots	Pass			
Conclusion	This product has passed the RFMD Qualification Requirements for production.					

Sample size and lot quantities reported are the minimum required for this qualification.